Report NO.: MG01978000092

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAE10P06
Package Type :	DFNWB3x3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	7.1363%
Lead Frame	Cu	7440-50-8	97.60%	52.2258%
	Fe	7439-89-6	2.20%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.10%	
	Pb	7439-92-1	0.01%	
	Ag	7440-22-4	0.01%	
Epoxy	Silver	7440-22-4	79.50%	1.9458%
	epoxy resin	9003-36-5	15.00%	
	1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	4.00%	
	dapsone	80-08-0	1.50%	
Wire	Copper	7440-50-8	99.9978%	0.8444%
	Other	/	0.0022%	
Mold Compound	Epoxy resin A	Trade Secret	3.00%	34.9839%
	Epoxy resin B	Trade Secret	3.00%	
	Phenol Resin	Trade Secret	3.00%	
	Silica(Amorphous) A	60676-86-0	83.50%	
	Silica(Amorphous) B	7631-86-9	7.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Sn	7440-31-5	99.90%	2.8637%
	Others	/	0.10%	